MC100E310

5V ECL Low Voltage 2:8 Differential Fanout Buffer

ON Semiconductor®

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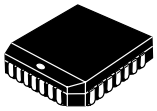
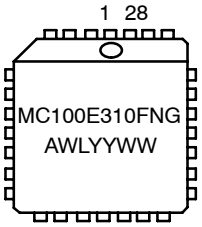


PLCC−28
FN SUFFIX
CASE 776

MARKING DIAGRAM*



A	= Assembly Location
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb−Free Package

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

Description

The MC100E310 is a low voltage, low skew 2:8 differential ECL fanout buffer designed with clock distribution in mind. The device features fully differential clock paths to minimize both device and system skew. The E310 offers two selectable clock inputs to allow for redundant or test clocks to be incorporated into the system clock trees.

The lowest TPD delay time results from terminating only one output pair, and the greatest TPD delay time results from terminating all the output pairs. This shift is about 10−20 pS in TPD. The skew between any two output pairs within a device is typically about 25 nS. If other output pairs are not terminated, the lowest TPD delay time results from both output pairs and the skew is typically 25 nS. When all outputs are terminated, the greatest TPD (delay time) occurs and all outputs display about the same 10 − 20 ps increase in TPD, so the relative skew between any two output pairs remains about 25 ns.

For more information on using PECL, designers should refer to ON Semiconductor Application Note AN1406/D.

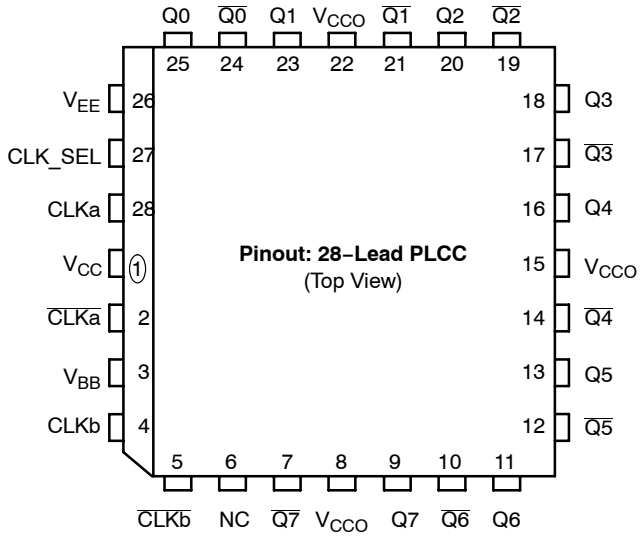
The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

The 100 Series Contains Temperature Compensation

Features

- Dual Differential Fanout Buffers
- 200 ps Part−to−Part Skew
- 50 ps Output−to−Output Skew
- 28−lead PLCC Packaging
- Q Output will Default LOW with Inputs Open or at V_{EE}
- PECL Mode Operating Range: V_{CC} = 4.2 V to 5.7 V with V_{EE} = 0 V
- NECL Mode Operating Range: V_{CC} = 0 V with V_{EE} = −4.2 V to −5.7 V
- Internal Input 50 kΩ Pulldown Resistors
- ESD Protection: Human Body Model; >2 kV, Machine Model; >200 V
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity Level: Pb = 1; Pb−Free = 3 For Additional Information, see Application Note AND8003/D
- Flammability Rating: UL 94 V−0 @ 0.125 in, Oxygen Index: 28 to 34
- Transistor Count = 212 devices
- Pb−Free Packages are Available*

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



* All V_{CC} and V_{CCO} pins are tied together on the die.

Warning: All V_{CC}, V_{CCO}, and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. Logic Diagram and Pinout Assignment

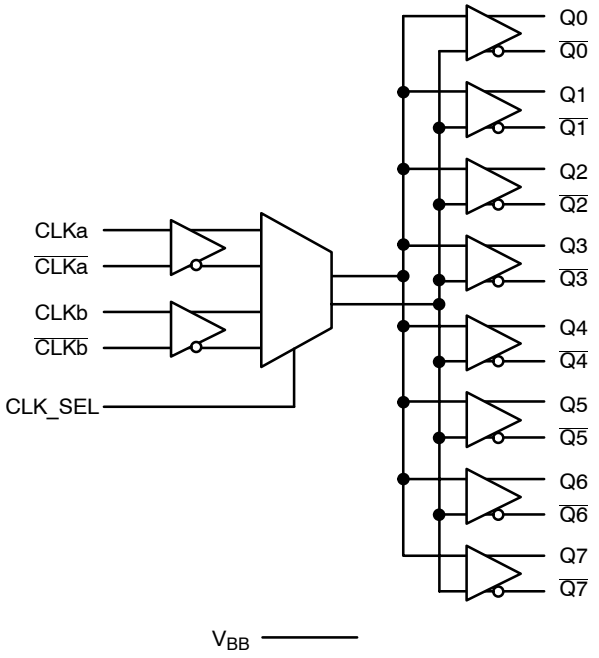


Figure 2. Logic Symbol

Table 1. PIN DESCRIPTION

PIN	Function
CLKa, CLKb; CLKa, CLKb Q0:7; Q0:7 CLK_SEL V_{BB} V_{CC}, V_{CCO} V_{EE} NC	ECL Differential Input Pairs ECL Differential Input Pairs ECL Differential Outputs ECL Input Clock Select Reference Voltage Output Positive Supply Negative Supply No Connect

Table 2. FUNCTION TABLE

PIN	Function
0 1	CLKa Selected CLKb Selected

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	PECL Mode Power Supply	V_{EE} = 0 V		8	V
V_I	PECL Mode Input Voltage NECL Mode Input Voltage	V_{EE} = 0 V V_{CC} = 0 V	$V_I \le V_{CC}$ $V_I \ge V_{EE}$	6 −6	V V
I_{out}	Output Current	Continuous Surge		50 100	mA mA
I_{BB}	V_{BB} Sink/Source			± 0.5	mA
T_A	Operating Temperature Range			0 to +85	°C
T_{stg}	Storage Temperature Range			−65 to +150	°C
θ_{JA}	Thermal Resistance (Junction−to−Ambient)	0 lfpm 500 lfpm	PLCC−28 PLCC−28	63.5 43.5	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction−to−Case)	Standard Board	PLCC−28	22 to 26	°C/W
T_{sol}	Wave Solder Pb Pb−Free			265 265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 4. 100E SERIES PECL DC CHARACTERISTICS V_{CCx} = 5.0 V; V_{EE} = 0 V (Note 1)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		55	60		55	60		65	70	mA
V_{OH}	Output HIGH Voltage (Note 2)	3915	3995	4120	3975	4050	4120	3975	4050	4120	mV
V_{OL}	Output LOW Voltage (Note 2)	3170	3305	3445	3190	3255	3380	3190	3260	3380	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	3835	3975	4120	3835	3975	4120	3835	3975	4120	mV
V_{IL}	Input LOW Voltage (Single−Ended)	3190	3355	3525	3190	3355	3525	3190	3355	3525	mV
V_{BB}	Output Voltage Reference	3.62		3.74	3.62		3.74	3.62		3.74	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	2.7		4.6	2.7		4.6	2.7		4.6	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5	0.3		0.5	0.25		0.5	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary −0.46 V / +0.8 V.
2. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.
3. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}.

Table 5. 100E SERIES NECL DC CHARACTERISTICS V_{CCx} = 0 V; V_{EE} = −5.0 V (Note 4)

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		55	60		55	60		65	70	mA
V_{OH}	Output HIGH Voltage (Note 5)	−1085	−1005	−880	−1025	−950	−880	−1025	−950	−880	mV
V_{OL}	Output LOW Voltage (Note 5)	−1830	−1695	−1555	−1810	−1745	−1620	−1810	−1740	−1620	mV
V_{IH}	Input HIGH Voltage (Single−Ended)	−1165	−1025	−880	−1165	−1025	−880	−1165	−1025	−880	mV
V_{IL}	Input LOW Voltage (Single−Ended)	−1810	−1645	−1475	−1810	−1645	−1475	−1810	−1645	−1475	mV
V_{BB}	Output Voltage Reference	−1.38		−1.26	−1.38		−1.26	−1.38		−1.26	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 6)	−2.3		−0.4	−2.3		−0.4	−2.3		−0.4	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	0.5	0.3		0.5	0.25		0.5	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

4. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary −0.46 V / +0.8 V.
5. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.
6. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}.

Table 6. AC CHARACTERISTICS V_{CCx} = 5.0 V; V_{EE}= 0 V or V_{CCx} = 0 V; V_{EE} = −5.0 V (Note 7)

		−40°C			25°C			85°C			
Symbol	**Characteristic**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**	**Unit**
f_{MAX}	Maximum Toggle Frequency	700	900		700	900		700	900		MHz
t_{PLH} t_{PHL}	Propagation Delay to Output IN (differential) (Note 8) IN (single−ended) (Note 9)	 525 500		 725 750	 550 550		 750 800	 575 600		 775 850	ps
t_{skew}	Within−Device Skew (Note 10) Part−to−Part Skew (Diff)			75 250			50 200			50 200	ps
t_{JITTER}	Random Clock Jitter (RMS)		< 1			< 1			< 1		ps
V_{PP}	Input Voltage Swing (Differential Configuration)	500			500			500			mV
t_r/t_f	Output Rise/Fall Time (20%−80%)	200		600	200		600	200		600	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

7. V_{EE} can vary −0.46 V / +0.8 V.
8. The differential propagation delay is defined as the delay from the crossing points of the differential input signals to the crossing point of the differential output signals. See *Definitions and Testing of ECLinPS AC Parameters* in Chapter 1 (page 1−12) of the ON Semiconductor High Performance ECL Data Book (DL140/D).
9. The single-ended propagation delay is defined as the delay from the 50% point of the input signal to the 50% point of the output signal.
10. The within−device skew is defined as the worst case difference between any two similar delay paths within a single device.

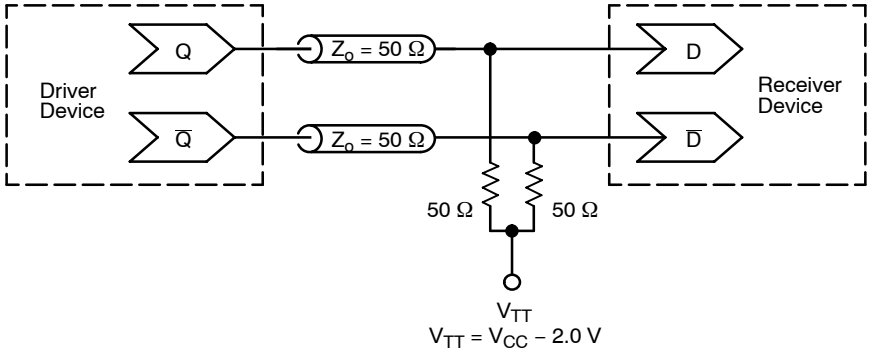


Figure 3. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping†
MC100E310FN	PLCC–28	37 Units / Rail
MC100E310FNG	PLCC–28 (Pb–Free)	37 Units / Rail
MC100E310FNR2	PLCC–28	500 / Tape & Reel
MC100E310FNR2G	PLCC–28 (Pb–Free)	500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D – ECL Clock Distribution Techniques

AN1406/D – Designing with PECL (ECL at +5.0 V)

AN1503/D – ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D – Metastability and the ECLinPS Family

AN1568/D – Interfacing Between LVDS and ECL

AN1672/D – The ECL Translator Guide

AND8001/D – Odd Number Counters Design

AND8002/D – Marking and Date Codes

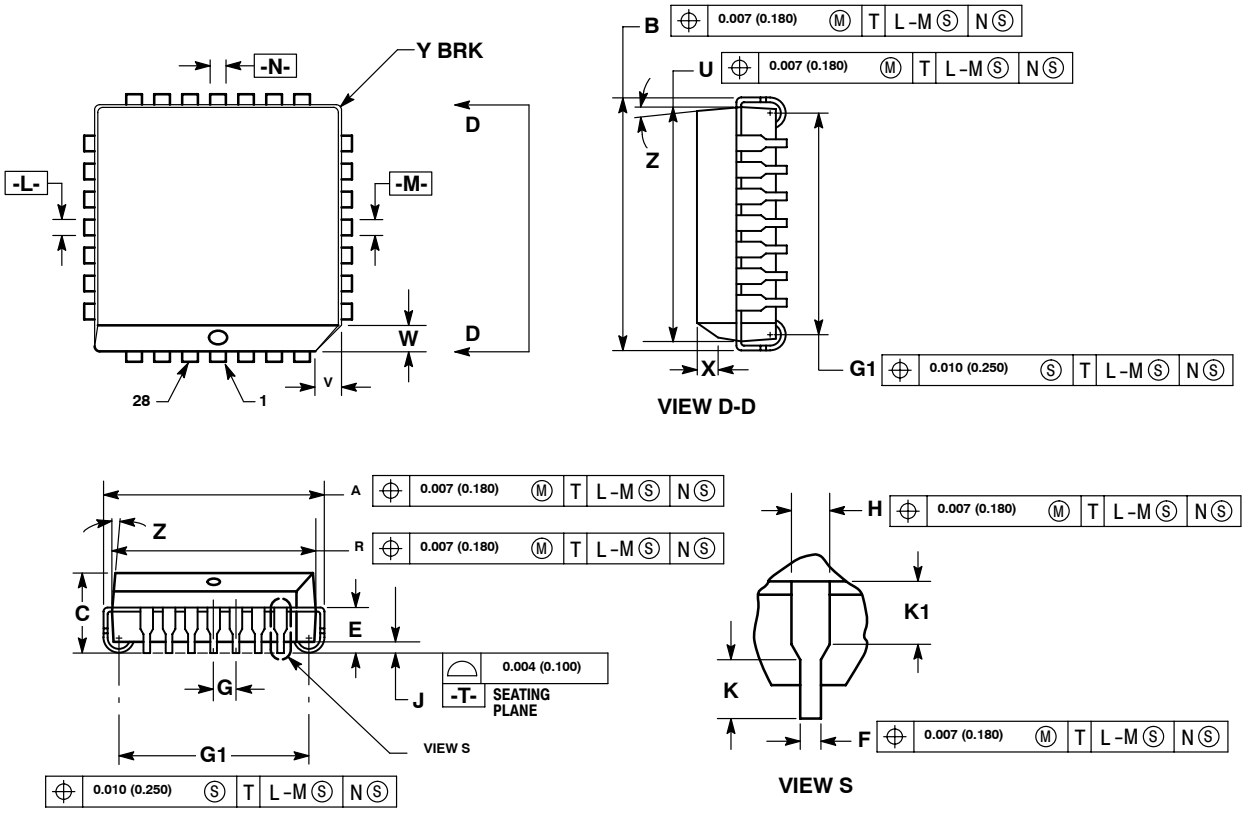
AND8020/D – Termination of ECL Logic Devices

AND8066/D – Interfacing with ECLinPS

AND8090/D – AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

PLCC−28
FN SUFFIX
PLASTIC PLCC PACKAGE
CASE 776−02
ISSUE E



NOTES:
1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIM G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
3. DIM R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.485	0.495	12.32	12.57
B	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	—	0.51	—
K	0.025	—	0.64	—
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	—	0.020	—	0.50
Z	2°	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040	—	1.02	—

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